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AND DEVICE MANUFACTURED THEREBY

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(Falls die Bezeichnung der Erfindung nicht angegeben ist, siehe Beschreibung.  
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Lithographic apparatus, device manufacturing method, and device manufactured thereby

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**Lithographic Apparatus, Device Manufacturing Method, and Device Manufactured Thereby.**

The present invention relates to a lithographic projection apparatus comprising:

- a radiation system for supplying a projection beam of radiation;
- a support structure for supporting patterning means, the patterning means serving to  
5 pattern the projection beam according to a desired pattern;
- a substrate table for holding a substrate; and
- a projection system for projecting the patterned beam onto a target portion of the substrate;
- a processing unit for processing the substrate before and/or after it has been  
10 exposed by the projection beam; and
- a transport unit for transporting the substrate between the substrate table and the processing unit.

15           The term “patterning means” as here employed should be broadly interpreted as referring to means that can be used to endow an incoming radiation beam with a patterned cross-section, corresponding to a pattern that is to be created in a target portion of the substrate; the term “light valve” can also be used in this context. Generally, the said pattern will correspond to a particular functional layer in a device being created in  
20 the target portion, such as an integrated circuit or other device (see below). Examples of such patterning means include:

- A mask. The concept of a mask is well known in lithography, and it includes mask types such as binary, alternating phase-shift, and attenuated phase-shift, as well as various hybrid mask types. Placement of such a mask in the radiation beam causes  
25 selective transmission (in the case of a transmissive mask) or reflection (in the case of a reflective mask) of the radiation impinging on the mask, according to the pattern on the mask. In the case of a mask, the support structure will generally be a mask table, which ensures that the mask can be held at a desired position in the

incoming radiation beam, and that it can be moved relative to the beam if so desired.

- A programmable mirror array. One example of such a device is a matrix-addressable surface having a viscoelastic control layer and a reflective surface. The basic principle behind such an apparatus is that (for example) addressed areas of the reflective surface reflect incident light as diffracted light, whereas unaddressed areas reflect incident light as undiffracted light. Using an appropriate filter, the said undiffracted light can be filtered out of the reflected beam, leaving only the diffracted light behind; in this manner, the beam becomes patterned according to the addressing pattern of the matrix-addressable surface. An alternative embodiment of a programmable mirror array employs a matrix arrangement of tiny mirrors, each of which can be individually tilted about an axis by applying a suitable localized electric field, or by employing piezoelectric actuation means. Once again, the mirrors are matrix-addressable, such that addressed mirrors will reflect an incoming radiation beam in a different direction to unaddressed mirrors; in this manner, the reflected beam is patterned according to the addressing pattern of the matrix-addressable mirrors. The required matrix addressing can be performed using suitable electronic means. In both of the situations described hereabove, the patterning means can comprise one or more programmable mirror arrays. More information on mirror arrays as here referred to can be gleaned, for example, from United States Patents US 5,296,891 and US 5,523,193, and PCT patent applications WO 98/38597 and WO 98/33096, which are incorporated herein by reference. In the case of a programmable mirror array, the said support structure may be embodied as a frame or table, for example, which may be fixed or movable as required.
- A programmable LCD array. An example of such a construction is given in United States Patent US 5,229,872, which is incorporated herein by reference. As above, the support structure in this case may be embodied as a frame or table, for example, which may be fixed or movable as required.

For purposes of simplicity, the rest of this text may, at certain locations, specifically direct itself to examples involving a mask and mask table; however, the general principles discussed in such instances should be seen in the broader context of the patterning means



as hereabove set forth.

Lithographic projection apparatus can be used, for example, in the manufacture of integrated circuits (ICs). In such a case, the patterning means may generate a circuit pattern corresponding to an individual layer of the IC, and this pattern can be  
5 imaged onto a target portion (*e.g.* comprising one or more dies) on a substrate (silicon wafer) that has been coated with a layer of radiation-sensitive material (resist). In general, a single wafer will contain a whole network of adjacent target portions that are successively irradiated via the projection system, one at a time. In current apparatus, employing patterning by a mask on a mask table, a distinction can be made between two different  
10 types of machine. In one type of lithographic projection apparatus, each target portion is irradiated by exposing the entire mask pattern onto the target portion in one go; such an apparatus is commonly referred to as a wafer stepper. In an alternative apparatus — commonly referred to as a step-and-scan apparatus — each target portion is irradiated by progressively scanning the mask pattern under the projection beam in a given reference  
15 direction (the "scanning" direction) while synchronously scanning the substrate table parallel or anti-parallel to this direction; since, in general, the projection system will have a magnification factor  $M$  (generally  $< 1$ ), the speed  $V$  at which the substrate table is scanned will be a factor  $M$  times that at which the mask table is scanned. More information with regard to lithographic devices as here described can be gleaned, for example, from US  
20 6,046,792, incorporated herein by reference.

In a manufacturing process using a lithographic projection apparatus, a pattern (*e.g.* in a mask) is imaged onto a substrate that is at least partially covered by a layer of radiation-sensitive material (resist). Prior to this imaging step, the substrate may undergo various procedures, such as priming, resist coating and a soft bake. After  
25 exposure, the substrate may be subjected to other procedures, such as a post-exposure bake (PEB), development, a hard bake and measurement/inspection of the imaged features. This array of procedures is used as a basis to pattern an individual layer of a device, *e.g.* an IC. Such a patterned layer may then undergo various processes such as etching, ion-implantation (doping), metallization, oxidation, chemo-mechanical polishing, etc., all  
30 intended to finish off an individual layer. If several layers are required, then the whole procedure, or a variant thereof, will have to be repeated for each new layer. Eventually, an array of devices will be present on the substrate (wafer). These devices are then separated

from one another by a technique such as dicing or sawing, whence the individual devices can be mounted on a carrier, connected to pins, etc. Further information regarding such processes can be obtained, for example, from the book "Microchip Fabrication: A Practical Guide to Semiconductor Processing", Third Edition, by Peter van Zant, McGraw Hill Publishing Co., 1997, ISBN 0-07-067250-4, incorporated herein by reference.

For the sake of simplicity, the projection system may hereinafter be referred to as the "lens"; however, this term should be broadly interpreted as encompassing various types of projection system, including refractive optics, reflective optics, and catadioptric systems, for example. The radiation system may also include components operating according to any of these design types for directing, shaping or controlling the projection beam of radiation, and such components may also be referred to below, collectively or singularly, as a "lens". Further, the lithographic apparatus may be of a type having two or more substrate tables (and/or two or more mask tables). In such "multiple stage" devices the additional tables may be used in parallel, or preparatory steps may be carried out on one or more tables while one or more other tables are being used for exposures. Dual stage lithographic apparatus are described, for example, in US 5,969,441 and WO 98/40791, incorporated herein by reference.

In lithographic apparatus it is important to minimize the contaminant level, especially in the environment surrounding the substrate immediately before and after it has been exposed by the projection beam. This is because the resist which is coated onto the substrate may react with the contaminants, marking the layer of resist. Sensitivity to these contaminants increases as the dimensions of the devices formed on the substrate decrease (due to the continual pressure to reduce the size of the devices), since smaller amounts of contaminant will produce marks that are the same order of size as the components to be formed on the substrate. Sensitivity also increases as the resists themselves become more sensitive to enable lower exposure doses and consequently faster throughput of the apparatus.

It is an object of the present invention to reduce the exposure of the resist on the substrate to contaminants.

This and other objects are achieved according to the invention in a

lithographic apparatus as specified in the opening paragraph, characterized by

- means for controlling the partial pressure of  $H_2O$  in the transport unit to be less than  $1 \times 10^{-2}$  mbar, the partial pressure of hydrocarbons in the transport unit to be less than  $1 \times 10^{-4}$  mbar and the partial pressure of ammonia in the transport unit to be less than  $1 \times 10^{-6}$  mbar.

This reduces the exposure of the resist on the substrate to contaminants during a significant portion of the time between the resist being applied to the substrate and the post exposure bake, after which the substrate is less sensitive to contaminants.

Preferably, the partial pressure of all contaminants in the transport unit is less than 1 mbar. Furthermore, the partial pressure of  $H_2O$  in the transport unit is preferably less than  $9 \times 10^{-6}$  mbar.

The partial pressure of the  $H_2O$  and other contaminants in the transport unit may be reduced by substantially evacuating the transport unit. This obviates the need for conditioning gases (for example, controlling the humidity level) or for providing filters to remove contaminants from the gases in the transport unit. In apparatus in which at least one of the chamber in which the substrate table is located and the processing unit is evacuated, this also significantly reduces the time required since time will not be lost raising or lowering the pressure as the substrate is transferred between the transport unit and another evacuated chamber. This may be the case for example where a dry development step is used. In this case both the exposure and the post exposure bake (PEB) are carried out at low pressure. Maintaining the transport unit also at a low pressure prevents time being lost raising and lowering the pressure of the atmosphere surrounding the substrate. Consequently the throughput of the apparatus is improved.

Alternatively, the partial pressure of  $H_2O$  and other contaminants in the transport unit may be controlled by providing a substantially contaminant-free gas to the transport unit. Again this obviates the need for conditioning and filtering the gas in the transport unit. Examples of such a contaminant-free gas include substantially pure nitrogen and synthetic air (a mixture of substantially pure nitrogen and substantially pure oxygen). This option for controlling the partial pressure of  $H_2O$  in the transport unit is also advantageous since it is relatively simple to effect.

The present invention is especially suited to apparatus which uses EUV as the radiation for the projection beam since the resists used are very sensitive.

Preferably the processing unit performs at least one of baking the substrate to fix the resist, cooling the substrate after it has been baked applying a layer of resist to the substrate and pre-aligning the substrate to determine its position and orientation before it is placed on the substrate table.

5                   According to a further aspect of the invention there is provided a device manufacturing method comprising the steps of:

- providing a substrate that is at least partially covered by a layer of radiation-sensitive material;
- providing a projection beam of radiation using a radiation system;
- 10   - using patterning means to endow the projection beam with a pattern in its cross-section;
- projecting the patterned beam of radiation onto a target portion of the layer of radiation-sensitive material,

characterized by transporting the substrate in a transport unit with a partial pressure of H<sub>2</sub>O  
15   less than  $1 \times 10^{-2}$  mbar, a partial pressure of hydrocarbons less than  $1 \times 10^{-4}$  mbar and the partial pressure of ammonia less than  $1 \times 10^{-6}$  mbar.

Although specific reference may be made in this text to the use of the apparatus according to the invention in the manufacture of ICs, it should be explicitly  
20   understood that such an apparatus has many other possible applications. For example, it may be employed in the manufacture of integrated optical systems, guidance and detection patterns for magnetic domain memories, liquid-crystal display panels, thin-film magnetic heads, etc. The skilled artisan will appreciate that, in the context of such alternative applications, any use of the terms "reticle", "wafer" or "die" in this text should be  
25   considered as being replaced by the more general terms "mask", "substrate" and "target portion", respectively.

In the present document, the terms "radiation" and "beam" are used to encompass all types of electromagnetic radiation, including ultraviolet radiation (*e.g.* with a wavelength of 365, 248, 193, 157 or 126 nm) and EUV (extreme ultra-violet radiation,  
30   *e.g.* having a wavelength in the range 5-20 nm), as well as particle beams, such as ion beams or electron beams.

Embodiments of the invention will now be described, by way of example only, with reference to the accompanying schematic drawings in which:

5                    Figure 1 depicts a lithographic projection apparatus according to an embodiment of the invention; and

Figure 2 depicts a transport unit according to the present invention.

10                   In the Figures, corresponding reference symbols indicate corresponding parts.

#### Embodiment 1

15                   Figure 1 schematically depicts a lithographic projection apparatus according to a particular embodiment of the invention. The apparatus comprises:

- a radiation system Ex, IL, for supplying a projection beam PB of radiation (*e.g.* EUV radiation), which in this particular case also comprises a radiation source LA;
- a first object table (mask table) MT provided with a mask holder for holding a mask MA (*e.g.* a reticle), and connected to first positioning means for accurately positioning the mask with respect to item PL;
- a second object table (substrate table) WT provided with a substrate holder for holding a substrate W (*e.g.* a resist-coated silicon wafer), and connected to second positioning means for accurately positioning the substrate with respect to item PL;
- a projection system ("lens") PL (*e.g.* mirror group) for imaging an irradiated portion of the mask MA onto a target portion C (*e.g.* comprising one or more dies) of the substrate W.

25                   As here depicted, the apparatus is of a reflective type (*e.g.* has a reflective mask). However, in general, it may also be of a transmissive type, for example (*e.g.* with a transmissive mask). Alternatively, the apparatus may employ another kind of patterning means, such as  
30                   a programmable mirror array of a type as referred to above.

The source LA (*e.g.* a laser-produced or discharge plasma source) produces a beam of radiation. This beam is fed into an illumination system (illuminator) IL, either

directly or after having traversed conditioning means, such as a beam expander Ex, for example. The illuminator IL may comprise adjusting means AM for setting the outer and/or inner radial extent (commonly referred to as  $\sigma$ -outer and  $\sigma$ -inner, respectively) of the intensity distribution in the beam. In addition, it will generally comprise various other  
5 components, such as an integrator IN and a condenser CO. In this way, the beam PB impinging on the mask MA has a desired uniformity and intensity distribution in its cross-section.

It should be noted with regard to Figure 1 that the source LA may be within the housing of the lithographic projection apparatus (as is often the case when the source  
10 LA is a mercury lamp, for example), but that it may also be remote from the lithographic projection apparatus, the radiation beam which it produces being led into the apparatus (e.g. with the aid of suitable directing mirrors); this latter scenario is often the case when the source LA is an excimer laser. The current invention and Claims encompass both of these scenarios.

15 The beam PB subsequently intercepts the mask MA, which is held on a mask table MT. Having been selectively reflected by the mask MA, the beam PB passes through the lens PL, which focuses the beam PB onto a target portion C of the substrate W. With the aid of the second positioning means (and interferometric measuring means IF), the substrate table WT can be moved accurately, e.g. so as to position different target  
20 portions C in the path of the beam PB. Similarly, the first positioning means can be used to accurately position the mask MA with respect to the path of the beam PB, e.g. after mechanical retrieval of the mask MA from a mask library, or during a scan. In general, movement of the object tables MT, WT will be realized with the aid of a long-stroke module (course positioning) and a short-stroke module (fine positioning), which are not  
25 explicitly depicted in Figure 1. However, in the case of a wafer stepper (as opposed to a step-and-scan apparatus) the mask table MT may just be connected to a short stroke actuator, or may be fixed.

The depicted apparatus can be used in two different modes:

1. In step mode, the mask table MT is kept essentially stationary, and an entire mask  
30 image is projected in one go (*i.e.* a single "flash") onto a target portion C. The substrate table WT is then shifted in the x and/or y directions so that a different target portion C can be irradiated by the beam PB;

2. In scan mode, essentially the same scenario applies, except that a given target portion C is not exposed in a single "flash". Instead, the mask table MT is movable in a given direction (the so-called "scan direction", e.g. the y direction) with a speed  $v$ , so that the projection beam PB is caused to scan over a mask image; concurrently, the substrate table WT is simultaneously moved in the same or opposite direction at a speed  $V = Mv$ , in which  $M$  is the magnification of the lens PL (typically,  $M = 1/4$  or  $1/5$ ). In this manner, a relatively large target portion C can be exposed, without having to compromise on resolution.

Figure 2 shows a transport device according to the present invention. It is attached to the chamber 10 surrounding the wafer table WT and a processing unit 11. The general function of the processing unit 11 is to prepare a substrate W before it is placed on the substrate table WT to be exposed and to perform steps necessary to fix the resist after the substrate has been exposed. To this end, the processing unit 11 may perform the steps of applying a resist to the substrate, pre-aligning the substrate to ascertain its position and orientation prior to being loaded onto the substrate table, baking the substrate to fix the resist and cooling the substrate to return it to ambient temperature after it has been baked. The transport unit 5 may also be attached to additional components. For example, as shown in Figure 2, the transport unit 5 is connected to a pre-alignment unit 12 that is not part of the processing unit 11. Furthermore, it is attached to a loading station 14 which allow substrates to be loaded into the apparatus.

The transport unit 5 of the present invention is enclosed in a chamber, sealing it from the environment in which the lithographic apparatus is located (normally a clean room). Within the chamber, contaminants are substantially excluded. For instance, the partial pressure of  $H_2O$  is below  $1 \times 10^{-2}$  mbar and preferably below  $9 \times 10^{-6}$  mbar, the partial pressure of hydrocarbons is below  $1 \times 10^{-4}$  mbar and the partial pressure of ammonia is below  $1 \times 10^{-6}$  mbar. The partial pressure of all contaminants combined is less than 1 mbar.

In order to provide the low contamination levels, the chamber in which the transport unit 5 is located may be evacuated. This is especially useful if the lithographic apparatus uses EUV radiation as the projection beam since the chamber 10 containing the substrate table is evacuated during exposure. Therefore, were the transport unit to operate at atmospheric pressure, time would be lost evacuating the chamber 10 housing the

substrate table WT after each substrate is loaded from the transport unit 5 to the substrate table WT.

Alternatively, the chamber housing the processing unit 5 may be supplied with a substantially pure gas, such as N<sub>2</sub> or synthetic air (a mixture of substantially pure N<sub>2</sub> and substantially pure O<sub>2</sub>). The pure gas is provided from a gas supply rather than filtering gas from the environment since to provide filters of a sufficiently high standard would be costly. Such filters would also be bulky. The pure gas displaces any gas from the environment within the chamber housing the transport unit 5, removing any contaminants. The pure gas in the chamber housing the transport unit 5 may be maintained at a pressure that is slightly higher than that of the ambient environment to ensure that any gas flow through apertures and leaks in the chamber surrounding the transport unit 5 flow into the ambient environment rather from it.

The processing unit is preferably contained in a chamber with similar conditions to the chamber housing the transport unit 5 (substantially evacuated or filled with substantially pure gas, for example). This reduces the risk of faults caused by contaminants in the processing unit 11 while the resist is sensitive, namely immediately prior to the substrate being exposed by the projection beam, immediately prior to the post-exposure bake, during the post-exposure bake and during the subsequent chilling process until the substrate has reached ambient temperature. Furthermore, by maintaining the processing unit 11 at the same conditions as the transport unit 5, no time is lost in transferring the substrate between the processing unit 11 and the transport unit 5. For example, neither unit will need to be pumped down to a substantially evacuated state immediately before or immediately after such a transfer.

As depicted in Figure 2, the transport unit 5 may be comprised of a plurality of substrate handling robots 15 that transfer the substrates between the different sections of the transport unit 5 and the components 10, 11, 12, 13, 14 attached to the transport unit 5. It will be appreciated, however, that, depending on the circumstance, the transport unit may be comprised of a single wafer handling robot 15 or may be comprised of some other transport apparatus, such as a conveyor belt.

Whilst specific embodiments of the invention have been described above, it will be appreciated that the invention may be practiced otherwise than as described. The description is not intended to limit the invention.



## CLAIMS:

1. A lithographic projection apparatus comprising:
  - a radiation system for providing a projection beam of radiation;
  - a support structure for supporting patterning means, the patterning means serving to pattern the projection beam according to a desired pattern;
  - a substrate table for holding a substrate;
  - a projection system for projecting the patterned beam onto a target portion of the substrate;
  - a processing unit for processing the substrate before and/or after it has been exposed to the projection beam; and
  - a transport unit for transporting the substrate between the substrate table and the processing unit;characterized by
  - means for controlling the partial pressure of  $\text{H}_2\text{O}$  in the transport unit to be less than  $1 \times 10^{-2}$  mbar, the partial pressure of hydrocarbons in the transport unit to be less than  $1 \times 10^{-4}$  mbar and the partial pressure of ammonia in the transport unit to be less than  $1 \times 10^{-6}$  mbar.
2. A lithographic projection apparatus according to claim 1, comprising means for controlling the partial pressure of contaminants in the transport unit to be less than 1 mbar.
3. A lithographic projection apparatus according to claim 1 or 2, wherein the means for controlling the partial pressure of  $\text{H}_2\text{O}$  in the transport unit controls it to be less than  $9 \times 10^{-6}$  mbar.
4. A lithographic projection apparatus according to claim 1, 2 or 3, wherein the means for controlling the partial pressure of  $\text{H}_2\text{O}$  in the transport unit substantially evacuates the transport unit.

5. A lithographic projection apparatus according to claim 4, wherein at least one of the space surrounding the substrate table and the processing unit is evacuated.
6. A lithographic projection apparatus according to claim 1, 2 or 3, wherein the means for controlling the partial pressure of H<sub>2</sub>O in the transport comprises a gas supply providing a substantially contaminant-free gas to fill the transport unit.
7. A lithographic projection apparatus according to claim 6, wherein the substantially contaminant-free gas is one of substantially pure nitrogen and synthetic air.
8. A lithographic projection apparatus according to any one of the preceding claims, wherein the projection beam of radiation is EUV radiation.
9. A lithographic projection apparatus according to any one of the preceding claims, wherein the processing unit performs at least one of the following steps:
  - bakes the substrate to fix the resist;
  - cools the substrate after it has been baked;
  - applies a layer of resist to the substrate; and
  - pre-aligns the substrate to ascertain its position and orientation before being placed on the substrate table.
10. A device manufacturing method comprising the steps of:
  - providing a substrate that is at least partially covered by a layer of radiation-sensitive material;
  - providing a projection beam of radiation using a radiation system;
  - using patterning means to endow the projection beam with a pattern in its cross-section;
  - projecting the patterned beam of radiation onto a target portion of the layer of radiation-sensitive material; and
  - transporting the substrate between the substrate table and a processing unit for processing the substrate before and/or after it has been exposed by the projection

beam;

characterized by transporting the substrate in a transport unit with a partial pressure of  $\text{H}_2\text{O}$  less than  $1 \times 10^{-2}$  mbar, a partial pressure of hydrocarbons less than  $1 \times 10^{-4}$  mbar and the partial pressure of ammonia less than  $1 \times 10^{-6}$  mbar.



ABSTRACT

**Lithographic Apparatus, Device Manufacturing Method, and Device Manufactured Thereby.**

Transfer of the substrate between the chamber 10 enclosing the substrate table WT and the processing unit 11 for preparing a substrate for exposure and processing it after exposure, in a substantially contaminant free environment to minimize the exposure of the resist on the substrate to the contaminants.

5 Fig. 2





